



Material Content Data Sheet



Sales Product Name	BTS50015-1TMA			Issued		29. August 2013		
MA#	MA000887164							
Package	PG-TO220-7-232			Weight*		2132.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.102	0.61	0.61	6144	6144
leadframe	non noble metal	iron	7439-89-6	1.501	0.07		704	
	inorganic material	phosphorus	7723-14-0	0.450	0.02		211	
	non noble metal	copper	7440-50-8	1498.593	70.28	70.37	702794	703709
wire	non noble metal	aluminium	7429-90-5	11.131	0.52	0.52	5220	5220
encapsulation	organic material	carbon black	1333-86-4	8.626	0.40		4045	
	plastics	epoxy resin	-	94.881	4.45		44496	
	inorganic material	silicondioxide	60676-86-0	471.529	22.11	26.96	221132	269673
leadfinish	non noble metal	tin	7440-31-5	23.005	1.08	1.08	10789	10789
plating	inorganic material	phosphorus	7723-14-0	0.009	0.00		4	
	non noble metal	nickel	7440-02-0	3.885	0.18	0.18	1822	1826
glue	plastics	Polyimide	26023-21-2	0.128	0.01	0.01	60	60
solder	noble metal	silver	7440-22-4	0.137	0.01		64	
	non noble metal	tin	7440-31-5	0.110	0.01		52	
	non noble metal	lead	7439-92-1	5.252	0.25	0.27	2463	2579
*deviation	< 10%				Sum in total:		100,00	1000000

Important Remarks:

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